IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.												
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						rials and M	ials and Mfg Information				
Supplier Inforn	nation																
Company name* Company				pany unique ID			Unique ID Authority					Respons	Response Date*				
onsemi													2025-07-13				
Contact Name			Title - Contact]	Phone - Contact*					Email -	Email - Contact*				
Product-Env-Stewa	ards	Product Enviro Compliance				NA NA					Product-Env-Stewards@onsemi.com						
uthorized Represe	entative*	Title - Representative]	Phone - Representative*					Email -	Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
Request	nuester Item Number Mfr Item Number NCV78763DQ66		m Number Mfr Item Name				Effective Da	ate Version N		Man	Manufacturing Site		Weigl	Weight* UOM		Unit Type	
			763DQ6AR2G	G PWR LED BST/2BCK 1.6A/60V			2025-07-13			PH1			515.45		mg	Each	
Manufacturing	Process Information	on															
Terminal	al Plating / Grid Array Material		Terminal Base Alloy		J-STD-020 M	TD-020 MSL Rating		Peak Process Body Temperatur		iture 1	are Max Time at Peak Tempe		rature Number of Reflow Cycles		les		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 3		3		260		C		30 seco		ıds	3			
Comments																	
TTENTION: MS	L 3 Rated item requires	Bake and I	Ory Pack (after	electrical test)													
or more informati	on regarding material co	omposition	please refer to	page 3													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	15.99	mg	Supplier	Silicon (Si)	7440-21-3		15.99	mg
Die Attach	2.86	mg		Epoxy resin	proprietary data		0.286	mg
			Supplier	Silver (Ag)	7440-22-4		2.288	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.286	mg
Lead Frame	172.4	mg	Supplier	Zinc (Zn)	7440-66-6		0.1724	mg
			Supplier	Iron (Fe)	7439-89-6		3.9652	mg
			Supplier	Copper (Cu)	7440-50-8		168.09	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1724	mg
Mold Compound-Black	322.04	mg		Epoxy resin	proprietary data		16.102	mg
			Supplier	Phenolic Resin	Proprietary Data		6.4408	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		8.051	mg
			Supplier	Carbon Black (C)	1333-86-4		1.6102	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		289.836	mg
Plating	1.62	mg	Supplier	Palladium (Pd)	7440-05-3		0.08	mg
			В	Nickel (Ni)	7440-02-0		1.4599	mg
			Supplier	Gold (Au)	7440-57-5		0.08	mg
Wire Bond - Au	0.54	mg	Supplier	Gold (Au)	7440-57-5		0.54	mg